

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An article comprising:

a substrate having a contact hole;

a display device mounted on one side of the substrate by an adhesive agent;

a thin film integrated circuit equipped on the other side of the substrate; [[and]]

a sealant;

a lead provided on the substrate;

a terminal provided in the display device;

a first wire electrically connected to the lead and the terminal; and

a second wire electrically connected to the lead and the thin film integrated circuit,

wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,

wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film,

wherein the thin film integrated circuit comprises a memory and a CPU, and

wherein the substrate, the display device, and the thin film integrated circuit are sealed with the sealant so that a pixel portion of the display device is exposed.

2. (Currently Amended) [[An]] The article according to claim 1, wherein the display device is a liquid crystal display device or a light emitting device.

3. (Canceled)

4. (Currently Amended) An article comprising:

a substrate having a contact hole;

a display device mounted on one side of the substrate by an adhesive agent;

a thin film integrated circuit equipped on the other side of the substrate; [[and]]

a sealant;

a lead provided on the substrate;

a terminal provided in the display device;

a first wire electrically connected to the lead and the terminal; and

a second wire electrically connected to the lead and the thin film integrated circuit,

wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,

wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film,

wherein the article has a thickness of from 0.05 mm to 1 mm,

wherein the thin film integrated circuit comprises a memory and a CPU, and

wherein the substrate, the display device, and the thin film integrated circuit are sealed with the sealant so that a pixel portion of the display device is exposed.

5. (Currently Amended) [[An]] The article according to claim 4, wherein the display device is a liquid crystal display device or a light emitting device.

6. (Canceled)

7. (Currently Amended) An article comprising:

a substrate having a contact hole;

a display device mounted on one side of the substrate by an adhesive agent; and

a thin film integrated circuit equipped on the other side of the substrate; [[and]]

a sealant;

a lead provided on the substrate;

a terminal provided in the display device;

a first wire electrically connected to the lead and the terminal; and

a second wire electrically connected to the lead and the thin film integrated circuit,

wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,

wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film,

wherein the display device is a passive matrix type or an active matrix type,

wherein the article has a thickness of from 0.05 mm to 1 mm,

wherein the thin film integrated circuit comprises a memory and a CPU, and

wherein the substrate, the display device, and the thin film integrated circuit are sealed with the sealant so that a pixel portion of the display device is exposed.

8. (Currently Amended) [[An]] The article according to claim 7, wherein the display device is a liquid crystal display device or a light emitting device.

9. (Canceled)

10. (Currently Amended) An article comprising:

a substrate having a contact hole;

a display device mounted on one side of the substrate by an adhesive agent; and

a plurality of thin film integrated circuits equipped on the other side of the substrate; [[and]]

a sealant;

a lead provided on the substrate;

a terminal provided in the display device;
a first wire electrically connected to the lead and the terminal; and
a second wire electrically connected to the lead and the thin film integrated
circuit,

wherein the display device is electrically connected to the plurality of thin film integrated circuits through the contact hole,

wherein each of the display device and the plurality of thin film integrated circuits comprises a polycrystalline semiconductor film,

wherein the plurality of thin film integrated circuits are laminated,

wherein the article has a thickness of from 0.05 mm to 1 mm,

wherein the thin film integrated circuit comprises a memory and a CPU, and

wherein the substrate, the display device, and the plurality of thin film integrated circuits are sealed with the sealant so that a pixel portion of the display device is exposed.

11. (Currently Amended) [[An]] The article according to claim 10, wherein thicknesses of the plurality of thin film integrated circuits are each from 1 μm to 5 μm .

12. (Currently Amended) [[An]] The article according to claim 10, wherein the display device is a liquid crystal display device or a light emitting device.

13. (Canceled)

14. (Currently Amended) [[An]] The article according to claim 1, wherein the substrate is a printed wiring board.

15. (Currently Amended) [[An]] The article according to claim 14, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

16. (Canceled)

17. (Currently Amended) [[An]] The article according to claim 1, further comprising a plurality of antenna coils.

18. (Currently Amended) [[An]] The article according to claim 4, wherein the substrate is a printed wiring board.

19. (Currently Amended) [[An]] The article according to claim 18, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

20. (Canceled)

21. (Currently Amended) [[An]] The article according to claim 4, further comprising a plurality of antenna coils.

22. (Currently Amended) [[An]] The article according to claim 7, wherein the substrate is a printed wiring board.

23. (Currently Amended) [[An]] The article according to claim 22, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

24. (Canceled)

25. (Currently Amended) [[An]] The article according to claim 7, further comprising a plurality of antenna coils.

26. (Currently Amended) [[An]] The article according to claim 10, wherein the substrate is a printed wiring board.

27. (Currently Amended) [[An]] The article according to claim 26, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

28. (Canceled)

29. (Currently Amended) [[An]] The article according to claim 10, further comprising a plurality of antenna coils.

30.-33. (Canceled)

34. (Currently Amended) [[An]] The article according to claim 1, wherein the display device has at least QVGA of resolution.

35. (Currently Amended) [[An]] The article according to claim 4, wherein the display device has at least QVGA of resolution.

36. (Currently Amended) [[An]] The article according to claim 7, wherein the display device has at least QVGA of resolution.

37. (Currently Amended) ~~[[An]]~~ The article according to claim 10, wherein the display device has at least QVGA of resolution.

38. (Currently Amended) ~~[[An]]~~ The article according to claim 1, wherein the thin film integrated circuit further comprises a driver circuit of the display device.

39. (Currently Amended) ~~[[An]]~~ The article according to claim 4, wherein the thin film integrated circuit further comprises a driver circuit of the display device.

40. (Currently Amended) ~~[[An]]~~ The article according to claim 7, wherein the thin film integrated circuit further comprises a driver circuit of the display device.

41. (Currently Amended) ~~[[An]]~~ The article according to claim 10, wherein the thin film integrated circuit further comprises a driver circuit of the display device.

42. (Currently Amended) ~~[[An]]~~ The article according to claim 1, wherein the substrate comprises a material having a thermal conductivity of from 2 W/mK to 30 W/mK.

43. (Currently Amended) ~~[[An]]~~ The article according to claim 4, wherein the substrate comprises a material having a thermal conductivity of from 2 W/mK to 30 W/mK.

44. (Currently Amended) ~~[[An]]~~ The article according to claim 7, wherein the substrate comprises a material having a thermal conductivity of from 2 W/mK to 30 W/mK.

45. (Currently Amended) [[An]] The article according to claim 10, wherein the substrate comprises a material having a thermal conductivity of from 2 W/mK to 30 W/mK.

46. (Currently Amended) [[An]] The article according to claim 1, wherein the adhesive agent is mixed with powder comprising silver, nickel, aluminum, or aluminum nitride, or filler.

47. (Currently Amended) [[An]] The article according to claim 4, wherein the adhesive agent is mixed with powder comprising silver, nickel, aluminum, or aluminum nitride, or filler.

48. (Currently Amended) [[An]] The article according to claim 7, wherein the adhesive agent is mixed with powder comprising silver, nickel, aluminum, or aluminum nitride, or filler.

49. (Currently Amended) [[An]] The article according to claim 10, wherein the adhesive agent is mixed with powder comprising silver, nickel, aluminum, or aluminum nitride, or filler.

50. (Currently Amended) [[An]] The article according to claim 1, wherein the article is an IC card.

51. (Currently Amended) [[An]] The article according to claim 4, wherein the article is an IC card.

52. (Currently Amended) [[An]] The article according to claim 7, wherein the article is an IC card.

53. (Currently Amended) ~~[[An]]~~ The article according to claim 10, wherein the article is an IC card.